

**HEWLETT-PACKARD COMPANY**  
 Intellectual Property Administration  
 P. O. Box 27100  
 Fort Collins, Colorado 80527-2400

PATENT APPLICATION

ATTORNEY DOCKET NO. 10007457 -1

**IN THE**  
**UNITED STATES PATENT AND TRADEMARK OFFICE**

Inventor(s): Jeffrey S Obert et al

Confirmation No.: 9544

Application No.: 09/888975

Examiner: Ahmed, S.

Filing Date: Jun 22, 2001

Group Art Unit: 1765

Title: SLOTTED SUBSTRATE AND SLOTTING PROCESS

**COMMISSIONER FOR PATENTS**  
 Washington, D.C. 20231

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application.

(X) Response/Amendment	(X) Petition to extend time to respond
(X) New fee as calculated below	( ) Supplemental Declaration
( ) No additional fee (Address envelope to "Box Non-Fee Amendments")	
( ) Other: _____	(fee \$ _____)

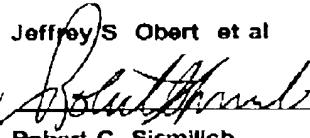
CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	22	MINUS	30	= 0	X \$18	\$ 0
INDEP. CLAIMS	4	MINUS	5	= 0	X \$84	\$ 0
[ ] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$280	\$ 0
EXTENSION FEE	1ST MONTH \$110.00	2ND MONTH \$410.00	3RD MONTH \$930.00	4TH MONTH \$1450.00		\$ 110
					OTHER FEES	\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 110

Charge \$ 110 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

Jeffrey S Obert et al

By



Robert C. Sismillch

Attorney/Agent for Applicant(s)  
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10007457

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Patent

**IN THE UNITED STATES  
PATENT AND TRADEMARK OFFICE**

**Inventors:** Jeffrey S. Obert, et al.

**Examiner:** S. Ahmed

**Serial No:** 09/888,975

**Group Art Unit:** 1765

**Filing Date:** June 22, 2001

**Title:** Slotted Substrate And Slotting Process

Assistant Commissioner For Patents  
Washington DC 20231

**AMENDMENT**

Sir:

In response to the action dated November 12, 2002, please amend the above-referenced application as follows:

**IN THE CLAIMS:**

Please amend claims 1, 11, and 24 as follows:

1. (Twice Amended) A method of manufacturing a slotted substrate comprising:
  - forming a masking layer over a front side of a substrate;
  - patterning and etching the masking layer to form a hole therethrough, wherein the hole exposes the substrate;
  - depositing a first layer over the masking layer and in the hole on the exposed substrate;
  - patterning and etching the first layer to form a plug in the hole; and
  - etching a back side of the substrate until a bottom surface of the plug is substantially exposed and a slot in the substrate is substantially formed, wherein the plug substantially plugs up the slot.